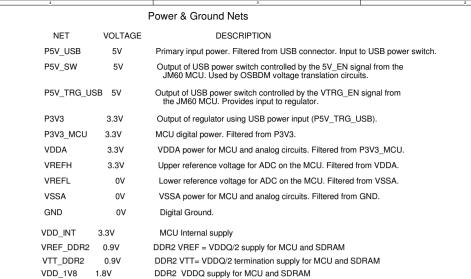
	5	
	Contents	
	1 HISTORY	
1 *		
5	K70N1M MCU-2	
6	USB/OSBDM/VTRAN/PWR	
7	PERIPHERALS	
8	ELEVATOR CONNECTORS	
9	SENSORS	
10	DDR2 SDRAM, NAND FLASH	
11	DDR POWER & TERMINATIONS	

	Revisions		
Rev	Description	Date	Approved
x1	A70 release placement	23 May 11	TTC
x2	preliminary schematics	27 May 11	TTC
A	Prototype release	22 Jul 11	TTC
AX1	Rev B changes 1.US3- Switch from socketed to non-socketed processor 2.SPI port connections added on secondary connector 3. Zero ohms R added on PTC16 and PTC17 to allow for disconnect from NAND. 4.FB_AD[31:24] is connected with EBI_D[7:0] on the primary. 5. Push button labels are placed at PTD0,PTE26 6. VrefH, VrefL are removed from	24 Oct 11	Peter, Melissa
	Primary elevator connector. 7.LCD Contrast tied at PTC18.		
	8.PTD0,PTD1 nets of U8 are renamed		
	9.Primary connector pin B21 is connected to PTE19, A9 is connected to PTE18		
	10.L3(IND_0805) is replaced with R143(R0805) zero ohms resistor		
	Schematics Alignment		
В	A085 Release	27 Oct 11	
B1	A085 Release - MCU Marketing part number updated as per MCO30515	3 Nov 11	Peter





ecified:

All polarized capacitors are aluminum electrolytic

2. Interrupted lines coded with the same letter or letter combinations are electrically connected.

varies with the manufacturer.

B Denotes - Active-Low Signal

<> or [] Denotes - Vectored Signals

5. Interpret diagram in accordance with American National Standards Institute specifications, current

revision, with the exception of logic block symbology.

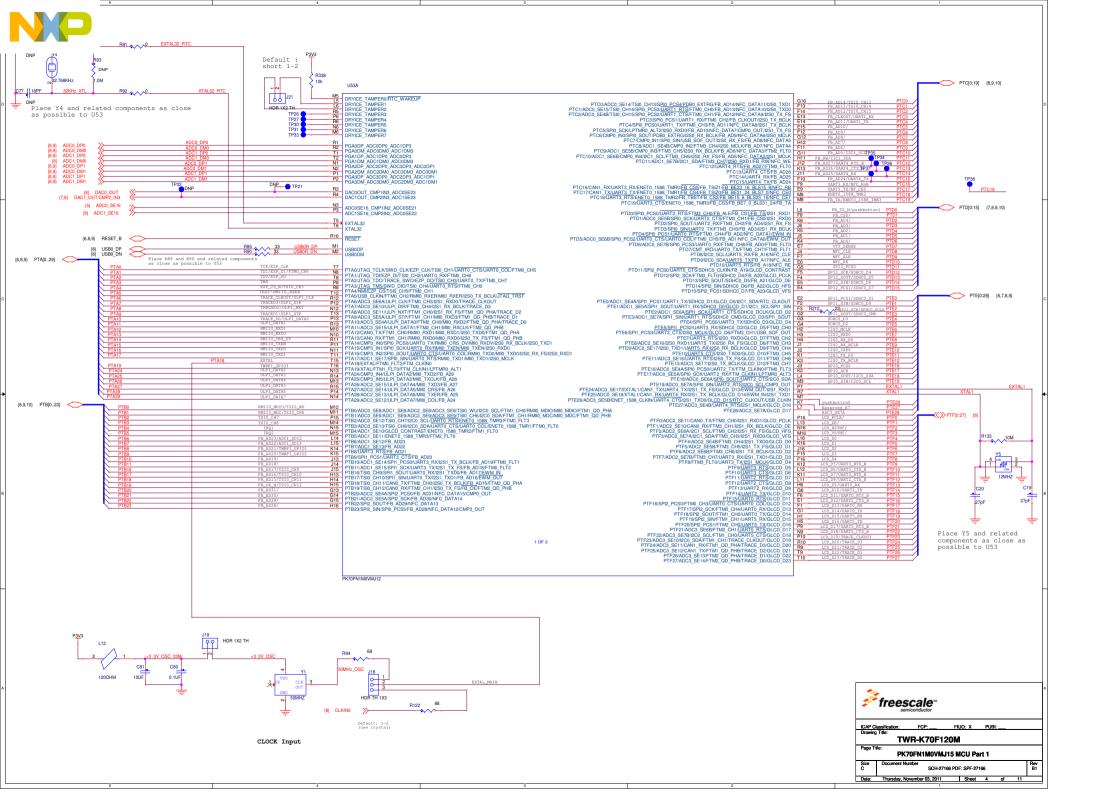
4. Special signal usage:

3. Device type number is for reference only. The number

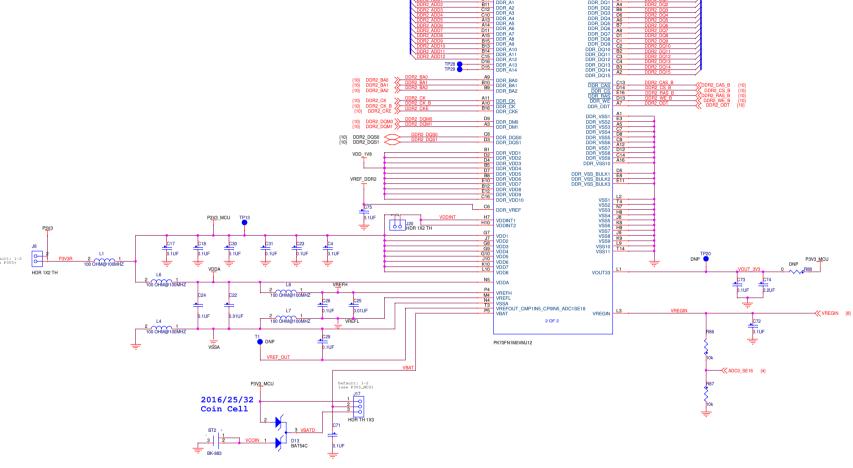
1 uF

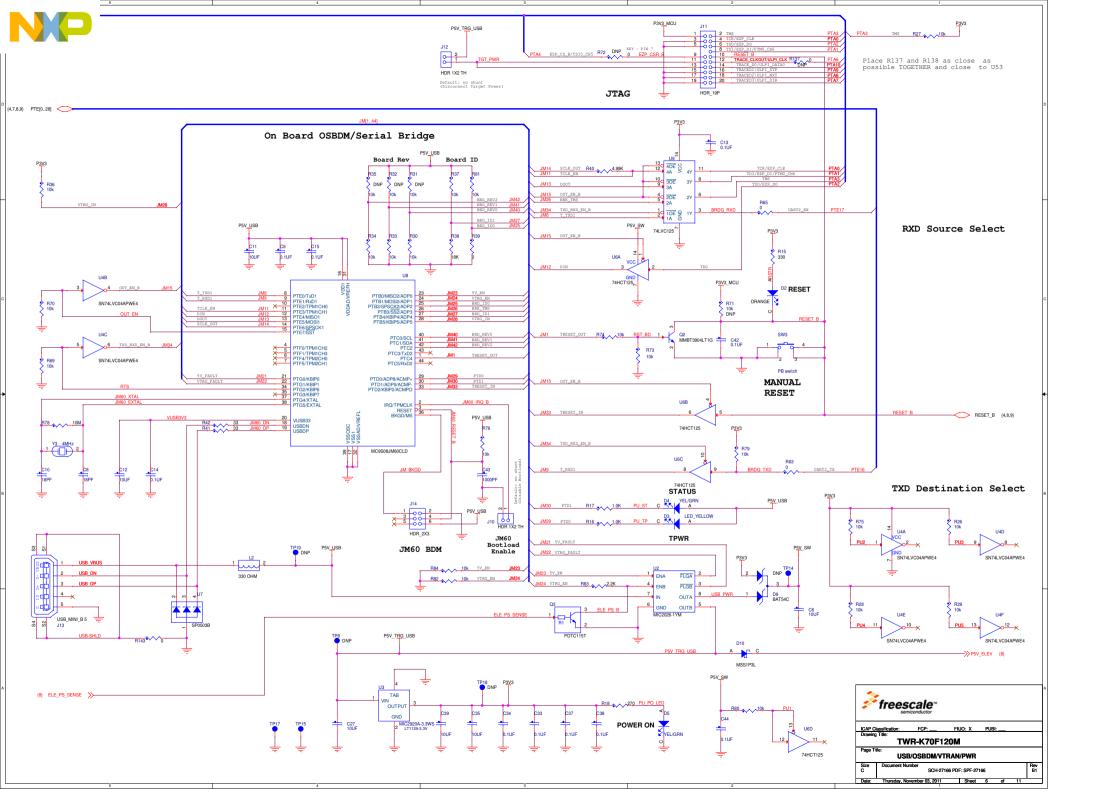


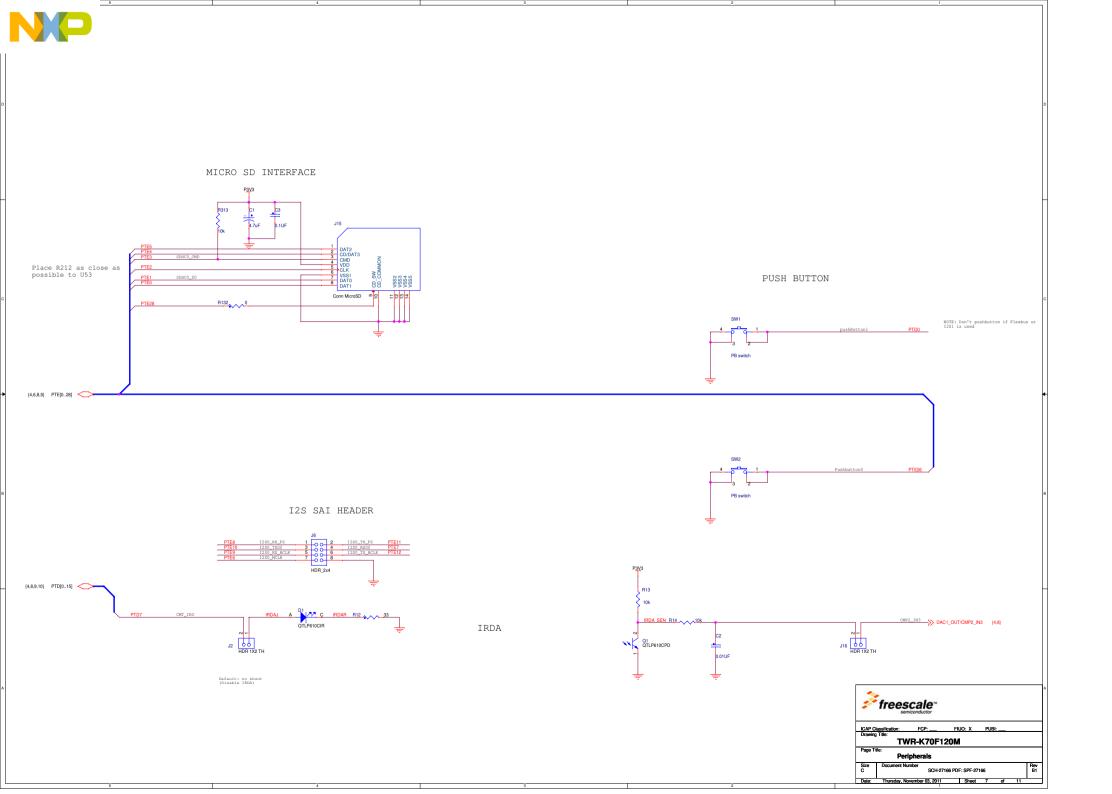




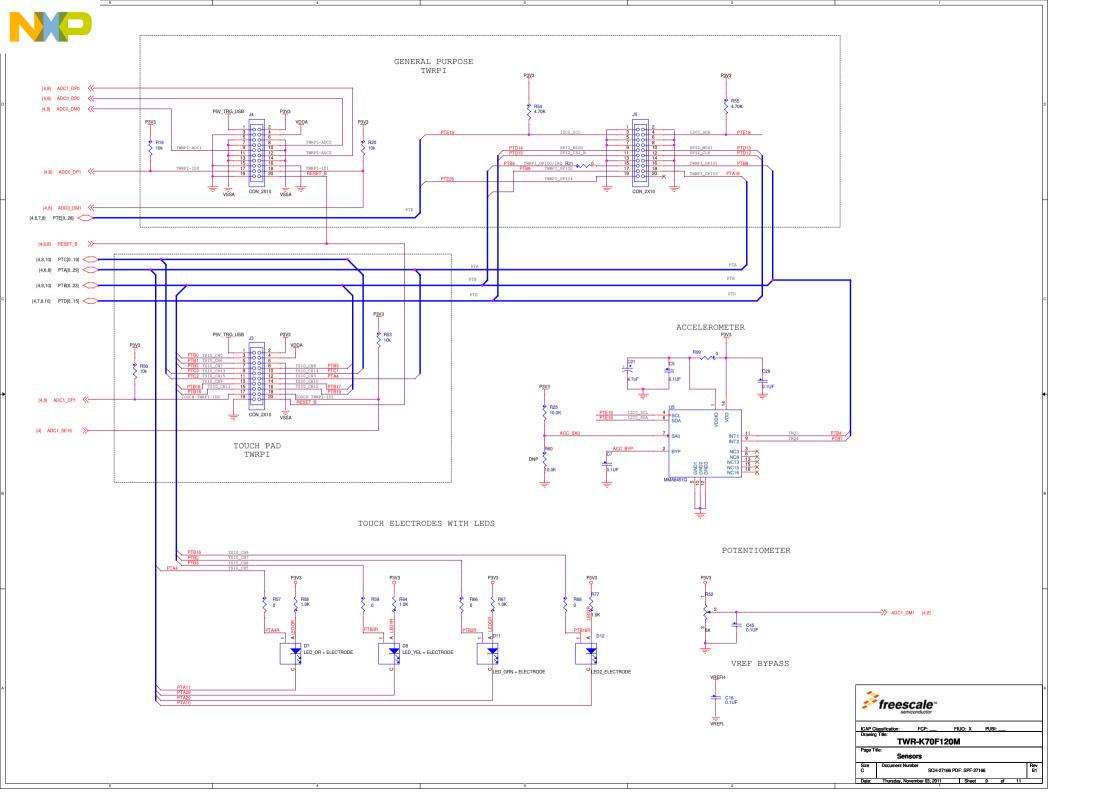
| Cont. Add | Cont

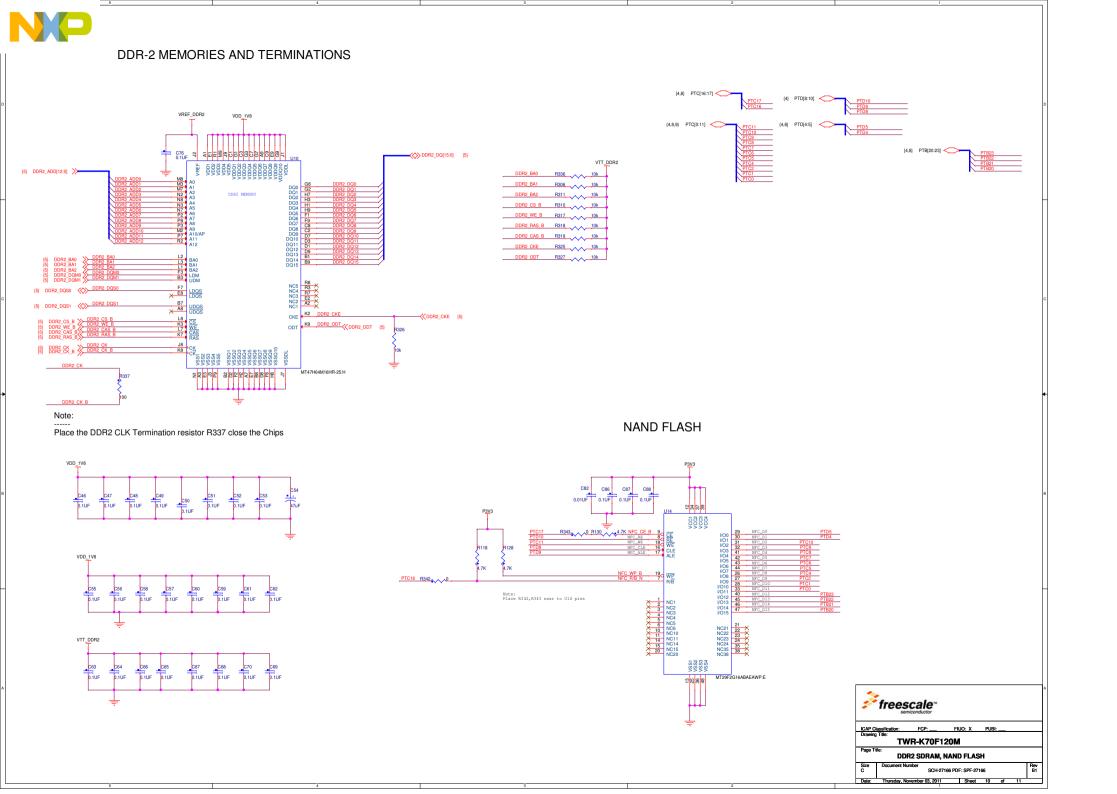






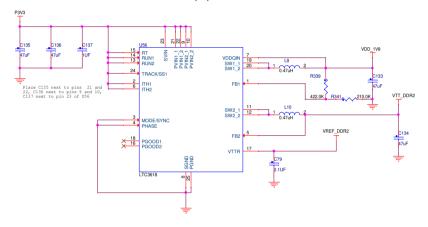
(4.6.9) PTA(0..29) (4.9.10) PTB(0.23) (4.9.10) PTC[0..19] < {4} PTF[0:27] (6) P5V_ELEV >> P3V3 P3V3 5V 2 GND-9 3.3V-4 3.3V-5 GND-10 GND-11 I2C0 SCL I2C0 SDA GPIO9IJARTI CTS GPIO9SSDHC D2 GPIO7/SD_WP_DET 5V.4 GND 25 3.3V_11 C2 GND 27 GND 27 (2C2 SCL 7 12C2 SDA GPIC2S ULPI STOP ULPI CLK D1 57 57 3 GND 17 3.3V 8 ELE PS SENSE 2 GND 18 GND 18 GND 19 ELE_PS_SENSE < ELE PS SENSE DNP R109 ULP_CAK
GPLOSS
ETH_MDG_2
ETH_MDG_2
ETH_RXDL_3
ETH_RXDL_3
GPLOSS_ETH_ACK_3
GPLOSS_ETH_CAK
GPLOSS_ETH_CAK
ULP_DATAMISS_TOUT_SKULP_DATAMISS_TOUT_SKULP_DATAMISS_TOUT_SKULP_DATAMISS_TOUT_SKULP_DATAMISS_TOUT_SKULP_DATAMISS_TOUT_SKULP_DATAMISS_TOUT_SKULP_DATAMISS_TOUT_SKULP_DATAMISS_TOUT_SKULP_DATAMISS_TOUT_SKULP_DATAMISS_TOUT_SKULP_DATAMISS_TOUT_SKULP_DATAMISS_TOUT_SKULP_DATAMISS_TOUT_SKANII_
ANII_ {4} CLKINO AN10 AN10 AN9 AN8 C30 C31 AND CONTROL OF THE CO GND_21 LCD_CLK/LCD_P26 CLON CLUNICD P26
THRET1
THRET1
THRET1
THRET1
THRET1
THRET0
GPF021
3.3V.9
PWM15
PPWM15
PPWM15
PPWM18
PWM18
PWM18
TO CANE, TX
TO PTB8 Place R11 as close to R137 and R138 as possible VSSA VDDA PTF7 HDR 1X2 TH LCD_D12/LCD_P12 LCD_D13/LCD_P13 USB0_DN {4}
USB0_DP {4} PTB4 R100 0 IRO1
PTB5 R101 0 IRO2
PTB6 R102 0 IRO3
PTB7 H00 0 IRO4
Lch 0 IRO4 GND_32 3.3V_14 C81 PCI EXPRESS TOWER SYSTEM PCI EXPRESS TOWER SYSTEM SECONDARY ***NOTE: EBI bus is equivalent to FB (FLEX BUS) from MCU *freescale* FIUO: X PUBI Place R107,R108 near to J7B TWR-K70F120M Place these R, If flow control needs to be tested, and remove R43.R44 Elevator Connector SCH-27166 PDF: SPF-27166







DDR-2 TERMINATION REG (3A)



	frees	cale™			
ICAP C	lassification:	FCP:	FIUO: X	PUBI:	
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